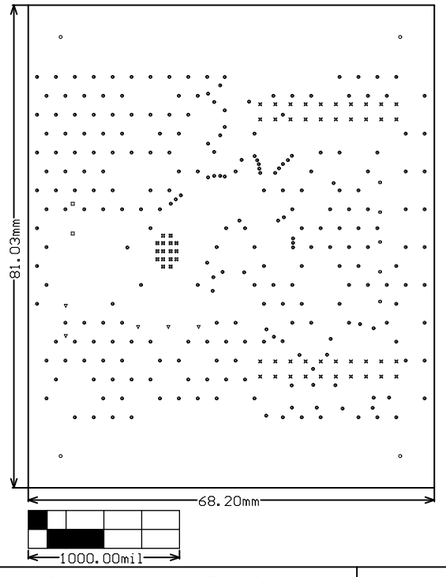
| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|---|---|---|---|---|---|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.40mil | 3.5 | |
| 1 | Top Layer | | 1.40mil | | |
| | Dielectric1 | FR-4 High Tg | 59.20mil | 4.8 | |
| 2 | Bottom Layer | | 1.40mil | | |
| | Bottom Solder | Solder Resist | 0.40mil | 3.5 | |
| | Bottom Overlay | | | | |




| Symbol | Quantity | Finished Hole Size | Plated | Hole Type | Drill Layer Pair | Hole Tolerance |
|---|---|---|---|---|---|---|
| ⊠ | 16 | 7.87mil (0.200mm) | PTH | Round | Top Layer - Bottom Layer | |
| ◎ | 259 | 10.00mil (0.254mm) | PTH | Round | Top Layer - Bottom Layer | |
| □ | 2 | 33.47mil (0.850mm) | PTH | Round | Top Layer - Bottom Layer | |
| ⊠ | 40 | 40.16mil (1.020mm) | PTH | Round | Top Layer - Bottom Layer | |
| ✡ | 5 | 47.24mil (1.200mm) | PTH | Round | Top Layer - Bottom Layer | |
| ▽ | 5 | 49.21mil (1.250mm) | PTH | Round | Top Layer - Bottom Layer | |
| ○ | 4 | 125.98mil (3.200mm) | PTH | Round | Top Layer - Bottom Layer | |
| | 331 Total | | | | | |

**DESIGN INFORMATION**

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 7.874 MIL
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER _____
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER_____
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER _____

BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER _____
SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER _____
☒ MATTE ☐ SEMI-GLOSS
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER _____
ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS --> ☐ 1 ☒ 2 ☐ 3
☒ RoHS ☐ OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
☐ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
☐ OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: DRV8316_2Layer_Thermal_Board
DESIGNED FOR: Public Release
FILE NAME: DRV8316_2Layer_PCB.PcbDoc

| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: N/A | REV: E1 | SVN REV: Not in version control |
| LAYER NAME = [illegible] | TID #: N/A | | |
| PLOT NAME = Fabrication Drawing | GENERATED : 7/21/2023 2:33:43 PM | | TEXAS INSTRUMENTS |

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| ENGINEER: | LAYOUT BY: |
|---|---|
| Joshua Horlander-Cruz | Joshua Horlander-Cruz |
| SCALE: 1.00 | ALTIUM DESIGNER VERSION: 23.5.1.21 |